

<b>PATENT ASSIGNMENT COVER SHEET</b>
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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
JOO HWAN JUNG	02/15/2021
JAE WOONG CHOI	02/15/2021
SEUNG EUN LEE	02/15/2021
YONG HOON KIM	02/15/2021
JIN WON LEE	02/15/2021
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<b>State/Country:</b>	KOREA, REPUBLIC OF
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	17196651
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<b>NAME OF SUBMITTER:</b>	ANGELA Y. ELLIS
<b>SIGNATURE:</b>	/Angela Y. Ellis/
<b>DATE SIGNED:</b>	03/09/2021
<b>Total Attachments: 2</b>	
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source=Declaration-Assignment#page2.tif	



other relevant treaties;

I hereby authorize and request the United States Patent and Trademark Office and officials in patent offices in foreign countries to issue any and all of said Letters Patent to the ASSIGNEE as the assignee of my entire right, title, and interest in and to the same, for the sole use and benefit of the ASSIGNEE, and its lawful successors and assigns, to the full end of the term for which said Letters Patent may be granted;

I hereby grant the attorney of record the power to insert on this Assignment any further identification that may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office or other authority for recordation of this document;

I hereby covenant that I have the full right to convey the interest assigned by this Assignment, and I have not executed and will not execute any agreement in conflict with this Assignment; and

Further, I hereby further covenant and agree that I will, without further consideration, communicate with the ASSIGNEE, and its lawful successors and assigns, any facts known to me respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said ASSIGNEE, and its lawful successors or assigns, execute all divisional, continuation, continuation-in-part, and reissue applications, make all rightful oaths and generally do everything possible to aid the ASSIGNEE, and its lawful successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the ASSIGNEE, and its lawful successors and assigns.

IN TESTIMONY WHEREOF, I have hereunto set my hands.

NAME OF INVENTOR (Full Legal Name) : Joo Hwan JUNG

Signature: Joo Hwan Jung Date: 15. 02. 2021

NAME OF INVENTOR (Full Legal Name) : Jae Woong CHOI

Signature: Jae Woong Choi Date: 15. 02. 2021

NAME OF INVENTOR (Full Legal Name) : Seung Eun LEE

Signature: [Handwritten Signature] Date: 15. 02. 2021

NAME OF INVENTOR (Full Legal Name) : Yong Hoon KIM

Signature: YONGHOON KIM Date: 15. 02. 2021

NAME OF INVENTOR (Full Legal Name) : Jin Won LEE

Signature: 이진원 Date: 15. 02. 2021

Morgan, Lewis & Bockius LLP